


Created date: 11/04/08	Technical Data Sheet <u>Alloy</u> <u>Sn 100 HT</u>	
Ref. : Alloy		
Updated :		

1 - GENERAL CHARACTERISTICS :

This material, dedicated to the soldering of traditional printed circuits and CMS, is manufactured using very high purity base tin, and following a process designed to reduce considerably superficial oxidation speed, insuring the quality of solder joints and the decrease of defects such as bridges, stalactites, flags,...

The amount of lead is less than 300 ppm.

The amount of phosphorus is between 50 and 90 ppm.

The quantity of produced oxides can be reduced to 30 up to 50%. This alloy is particularly dedicated to the soldering with no-clean fluxes.

The amount of metallic impurities are very lower than those required by the national and international standards.

This alloy is compliant with the RoHS 2002/95/CE directive concerning the removal of lead in soldering alloys.

2 - PHYSIOCHEMICAL CHARACTERISTICS :

- 2.1. Amount of Tin : 100%
- 2.2. Tin for first melting : global purity > 99.95%
- 2.3. Maximum content of impurities : see below

Cu	Ag	Cd	Sb	Bi	Fe	Zn	Al	As	S	Cl	Pb	Other
0.05 %	0.005%	0.002%	0.05%	0.01%	0.02%	0.001%	0.001%	0.01%	0.001%	0.001%	0.03%	0.05%

- 2.4. Form : Bars, sticks, granules.
Other: on request.
- 2.5. Melting point : 232°C
- 2.6. Working temperature : 250°C to 260°C
- 2.7. Specific weight : 7.3

3 - FURTHER INFORMATION :

- 3.1. Packaging : Bars or sticks in cartons of 20 ~ 25 Kg.
Other: on request.
- 3.2. Storage : In original packaging, at an average temperature of 20°C.